Fast-Acting Brick SMD Fuse
2611

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Description

The SMD fuse for the small size and good electrical performance reliability and quality the solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical brick fuses.

Features

- Rapid interruption of excessive current
- Ceramic body and silver plated copper terminal
- Excellent environmental integrity
- One time positive disconnect
- Lead-free and Halogen-free
- Designed to UL 248-14/ IEC 60068-2-58/ MIL-STD-202

Specifications

|	
Operating Temperature	: -55°C to +125°C
Storage Conditions	: +10°C to +60°C
Relative Humidity	: ≤ 75% yearly average without dew, maximum 30 days at 95%
Vibration Resistance	: 24 cycles at 15 min. each
	10-60Hz at 0.75mm amplitude
	60-2000Hz at 10g acceleration

Electrical Characteristics

Part Number	Rated Current	Max. Voltage	Typical Voltage Drop (mV)	Breaking Capacity	Nominal Melting I²t (A²sec)	Typical Cold Resistance (Ω)
MP001615	1A	250V AC 400V DC	300	150A@125V AC/250V AC 150A@125V DC/250V DC 400V DC 50A, 350V DC/400V DC 100A	0.47	147.8

Note:

(1) Permissible continuous operating current is ≤100% at ambient temperature of 23°C (73.4°F)

(2) The current values used for calculating I^2T should be within the standard range of 10ms.

Temperature Derating Curve

Temperature Derating Curve
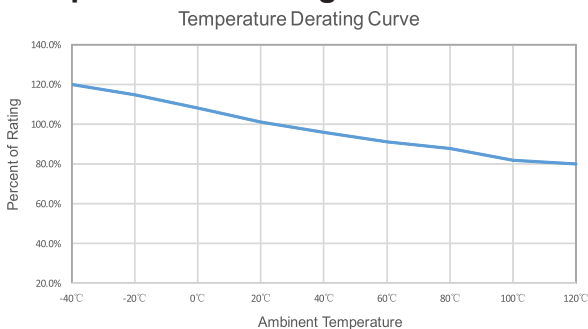
$$\text{Calculation for ideal fuse selection} = \frac{\text{Operating Current (A)}}{\text{Rating (\% × 0.75)}}$$

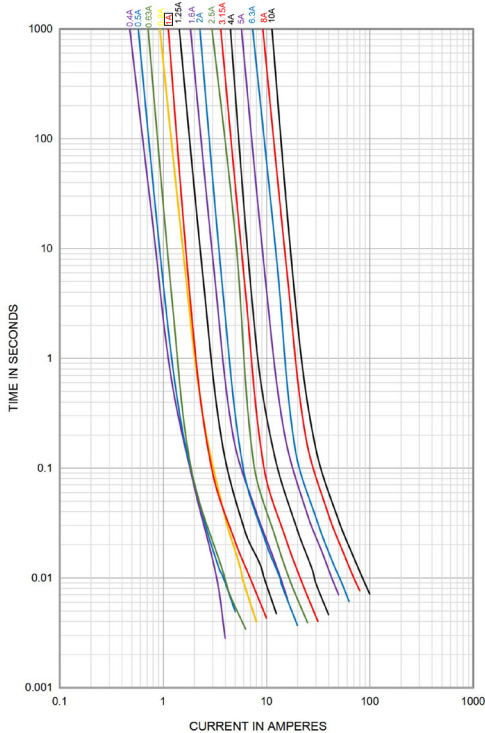Newark.com/multicomp-pro
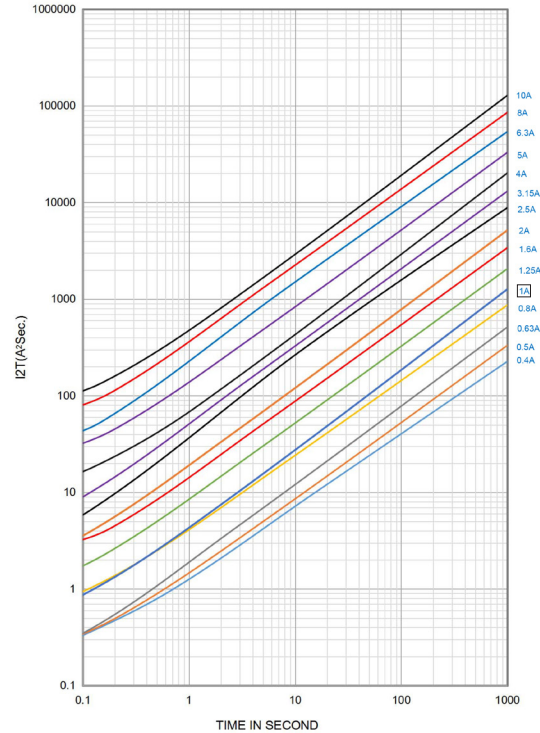Farnell.com/multicomp-pro
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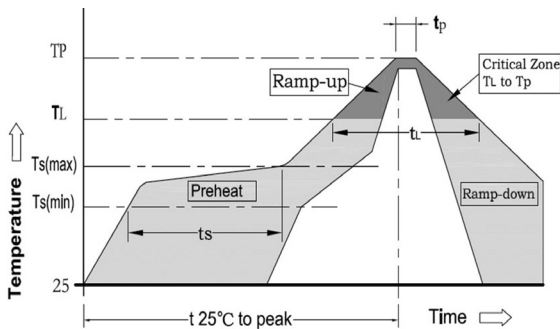
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Average Time Current (I-T) Curves

I²T

Soldering Parameters

1. Infrared Reflow:

   Temperature: 260°C

   Time: 5sec Max.

   Recommend reflow profile

2. Wave Soldering:

   Reservoir Temperature: 260°C

   Time in Reservoir: 10sec Max.

3. Hand Soldering

   Temperature: 300°C

   Time: 3 sec. Max.

   Soldering iron avoid touch Brass Cap.
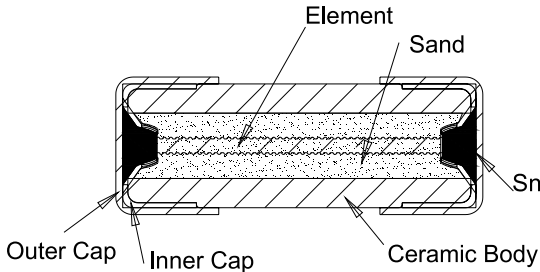
Profile Feature		Pb-Free Assembly
Average Ramp-UP Rate(Tsmax to Tp)		3°C/s Max.
Preheat	Temperature Min (Ts min)	150°C
	Temperature Max (Ts max)	200°C
	Time (Tsmin to Ts max)	60sec to 120sec
Peak Temperature (TP)		260°C
Time within 5°C of actual Peak Temperature(TP)		5sec
Melting tin time (TL)		20sec to 40sec
Ramp-Down Rate		6°C/s Max.
Time 25°C to Peak Temperature(TP)		8 minutes Max.

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Mechanical Specifications

Element
Sand
Sn
Outer Cap
Inner Cap
Ceramic Body

Diagram

11.3±0.5
3±0.5
4±0.2
4±0.2

Packing Information

4.0±0.1
1.5±0.1
1.75±0.1
2.0±0.1
24±0.3
8±0.4
8±0.1
4.5±0.1
0.35±0.05
4.65±0.1
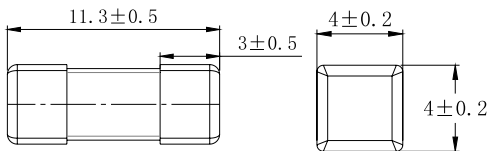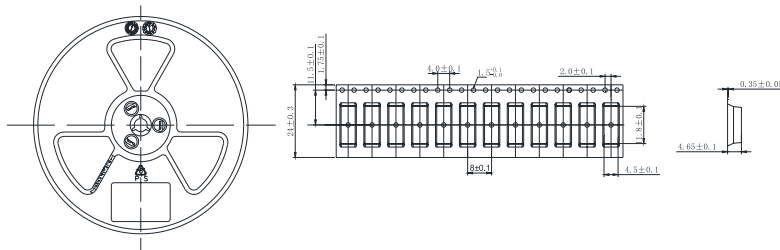
Dimensions : Millimetres

Part Number Table

Description	Part Number
Brick SMD Fuse, Time-Lag, 1A, 250V AC/400V DC, 2611	MP001615

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